	Material Composit © Copyright 2005. IPC, I nternational and Pan-Am	Bannockbi	urn, Illinois. A	ll rights reserved untions.	under both	This docum level parts,	ent is a declar the declaration	ation of th	ne substance asses all low	s within the ma er level materia	nufacture ils for wh	er listed ite nich the ma	m. Note: inufactur	if the item is an a er has engineering	ssembly with lower responsibility.	
					Form Type Distribute	<ul> <li>Declaration Class *</li> <li>Class 6 - RoHS Yes/No, Homogeneous Mater</li> </ul>					s Materia	ials and Mfg Information				
Supplier Informat	ion															
Company name*			Company unique ID			Unique ID Authority					Response Date*					
onsemi												2024-04-20				
Contact Name Ti			Title - Contact			Phone - Contact*					Email - Contact*					
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Requester Item Number Mfr Item		Mfr Item	n Number Mfr Item Name				Effective Da	te Vers	ion	Manufacturing Site		W	eight*	UOM	Unit Type	
		DAP222T1G		SS SC75 SWCH DIODE 80V			2024-04-20			CN1		2.	51	mg	Each	
Manufacturing Pro	occess Information	I		•			•									
Terminal Plating / Grid Array Material Terminal F			erminal Base A	Alloy	J-STD-020 MS	L Rating	Peak Pr	ocess Bod	ly Temperat	ure Max Time	at Peak	Temperatu	re Nun	nber of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy			U Alloy		1		260		С	30		second	s 3			
Comments																
level 1 - maximum time	e at peak temperature d	uring sole	dering is 10-3	0 seconds												
For more information 1	regarding material com	position p	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth					
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted				
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all				
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature Ra	stislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).				-	_		-
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.06	mg	Supplier	Silicon (Si)	7440-21-3		0.06	mg
Lead Frame	0.75	mg	В	Nickel (Ni)	7440-02-0		0.2843	mg
			Supplier	Iron (Fe)	7439-89-6		0.393	mg
			Supplier	Copper (Cu)	7440-50-8		0.0727	mg
Mold Compound-Black	1.57	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.157	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0078	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.2277	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.0205	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.157	mg
Plating	0.12	mg	Supplier	Tin (Sn)	7440-31-5		0.12	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg